

IN THE CLAIMS:

Please amend the claims as follows.

1. (Currently Amended) A multiplayer circuit board, comprising:

a substrate having a first surface and a second surface extending from an end of the first surface at a required angle relative to the first surface;

a multiplayer circuit formed on the first surface of said substrate and composed of a plurality of circuit layers, each of which is provided with a conductive layer having a required circuit pattern and an insulation layer formed on said conductive layer by film formation;

a second conductive layer formed on the second surface of said substrate, by which said conductive layer of one of said circuit layers is electrically connected to said conductive layer of another one of said circuit layers, wherein the second surface of said substrate includes a side surface of a projection on the first surface.

2. (Cancelled)

3. (Currently Amended) The multilayer circuit board as set forth in claim 1, wherein the said first surface is a top surface of said substrate, and the second surface ~~is~~ further includes a side surface of said substrate.

4. (Original) The multilayer circuit board as set forth in claim 1, wherein the required angle between the first and second surfaces is an obtuse angle.

5. (Currently Amended) ~~The multilayer circuit board as set forth in claim 1, A~~
multiplayer circuit board, comprising:

a substrate having a first surface and a second surface extending from an end of
the first surface at a required angle relative to the first surface;

a multiplayer circuit formed on the first surface of said substrate and composed of
a plurality of circuit layers, each of which is provided with a conductive layer having a
required circuit patter and an insulation layer formed on said conductive layer by film
formation;

a second conductive layer formed on the second surface of said substrate, by
which said conductive layer of one of said circuit layers is electrically connected to said
conductive layer of another one of said circuit layers a layer-to-layer connection of said
multilayer circuit is made, wherein said multilayer circuit has an aperture, through which
a part of the first surface is exposed, and an electronic device is mounted in a concave
formed in the exposed first surface, and an electrical connection between said multilayer
circuit and said electronic device is made by a third conductive layer formed on an inner
surface of said concave.

6. (Original) The multilayer circuit board as set forth in claim 1, wherein said second
conductive layer is a plurality of second conductive layers to obtain plural layer-to-layer
connections of said multilayer circuit, and each of said conductive layers is separated
from an adjacent second conductive layer in the thickness direction by a second
insulation layer.

7. (Currently Amended) ~~The multilayer circuit board as set forth in claim 1,~~ A
multiplayer circuit board, comprising:

a substrate having a first surface and a second surface extending from an end of
the first surface at a required angle relative to the first surface;

a multiplayer circuit formed on the first surface of said substrate and composed of
a plurality of circuit layers, each of which is provided with a conductive layer having a
required circuit patter and an insulation layer formed on said conductive layer by film
formation;

a second conductive layer formed on the second surface of said substrate, by
which said conductive layer of one of said circuit layers is electrically connected to said
conductive layer of another one of said circuit layers a layer-to-layer connection of said
multilayer circuit is made, wherein said substrate has a third surface extending at a
different level from the first surface and a fourth surface extending from the other end of
the first surface to an end of the third surface, and said multilayer circuit is formed on the
first, third, and fourth surfaces of said substrate, and said second conductive layer is
formed on the second surface that is a side surface of a projection on the first surface to
make the layer-to-layer connection of said multilayer circuit.